

PATENT ASSIGNMENT

Electronic Version v1.1
 Stylesheet Version v1.1

| SUBMISSION TYPE: | NEW ASSIGNMENT | | | | | | | | | | | | |
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| NATURE OF CONVEYANCE: | ASSIGNMENT | | | | | | | | | | | | |
| CONVEYING PARTY DATA | | | | | | | | | | | | | |
| <table border="1"> <thead> <tr> <th>Name</th> <th>Execution Date</th> </tr> </thead> <tbody> <tr> <td>Musubu ICHIKAWA</td> <td>01/23/2013</td> </tr> <tr> <td>Hyeon-Gu JEON</td> <td>01/23/2013</td> </tr> <tr> <td>Naomi OGUMA</td> <td>01/23/2013</td> </tr> <tr> <td>Naoki HIRATA</td> <td>01/23/2013</td> </tr> <tr> <td>Hisao KONO</td> <td>01/23/2013</td> </tr> </tbody> </table> | | Name | Execution Date | Musubu ICHIKAWA | 01/23/2013 | Hyeon-Gu JEON | 01/23/2013 | Naomi OGUMA | 01/23/2013 | Naoki HIRATA | 01/23/2013 | Hisao KONO | 01/23/2013 |
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| <table border="1"> <tr> <td>Name:</td> <td>SHINSHU UNIVERSITY</td> </tr> <tr> <td>Street Address:</td> <td>1-1, Asahi 3-chome</td> </tr> <tr> <td>City:</td> <td>Matsumoto-shi, Nagano</td> </tr> <tr> <td>State/Country:</td> <td>JAPAN</td> </tr> <tr> <td>Postal Code:</td> <td>390-8621</td> </tr> </table> | | Name: | SHINSHU UNIVERSITY | Street Address: | 1-1, Asahi 3-chome | City: | Matsumoto-shi, Nagano | State/Country: | JAPAN | Postal Code: | 390-8621 | | |
| Name: | SHINSHU UNIVERSITY | | | | | | | | | | | | |
| Street Address: | 1-1, Asahi 3-chome | | | | | | | | | | | | |
| City: | Matsumoto-shi, Nagano | | | | | | | | | | | | |
| State/Country: | JAPAN | | | | | | | | | | | | |
| Postal Code: | 390-8621 | | | | | | | | | | | | |
| <table border="1"> <tr> <td>Name:</td> <td>DAINICHISEIKA COLOR & CHEMICALS MFG. CO., LTD.</td> </tr> <tr> <td>Street Address:</td> <td>7-6, Nihonbashi Bakuro-cho 1-chome, Chuo-ku</td> </tr> <tr> <td>City:</td> <td>Tokyo</td> </tr> <tr> <td>State/Country:</td> <td>JAPAN</td> </tr> <tr> <td>Postal Code:</td> <td>103-8383</td> </tr> </table> | | Name: | DAINICHISEIKA COLOR & CHEMICALS MFG. CO., LTD. | Street Address: | 7-6, Nihonbashi Bakuro-cho 1-chome, Chuo-ku | City: | Tokyo | State/Country: | JAPAN | Postal Code: | 103-8383 | | |
| Name: | DAINICHISEIKA COLOR & CHEMICALS MFG. CO., LTD. | | | | | | | | | | | | |
| Street Address: | 7-6, Nihonbashi Bakuro-cho 1-chome, Chuo-ku | | | | | | | | | | | | |
| City: | Tokyo | | | | | | | | | | | | |
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| PROPERTY NUMBERS Total: 1 | | | | | | | | | | | | | |
| <table border="1"> <thead> <tr> <th>Property Type</th> <th>Number</th> </tr> </thead> <tbody> <tr> <td>Application Number:</td> <td>13819636</td> </tr> </tbody> </table> | | Property Type | Number | Application Number: | 13819636 | | | | | | | | |
| Property Type | Number | | | | | | | | | | | | |
| Application Number: | 13819636 | | | | | | | | | | | | |
| CORRESPONDENCE DATA | | | | | | | | | | | | | |
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| ATTORNEY DOCKET NUMBER: | 20344.0029USWO |
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| NAME OF SUBMITTER: | Douglas P. Mueller |
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| Total Attachments: 4 source=Assignment_0029#page1.tif source=Assignment_0029#page2.tif source=Assignment_0029#page3.tif source=Assignment_0029#page4.tif |
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Docket No.

ASSIGNMENT OF PATENT APPLICATION

WHEREAS,

1. ICHIKAWA, Musubu residing at c/o c/o SHINSHU UNIVERSITY FACULTY OF TEXTILE SCIENCE AND TECHNOLOGY. and a citizen of Japan
2. JEON, Hyeon-Gu residing at c/o c/o SHINSHU UNIVERSITY FACULTY OF TEXTILE SCIENCE AND TECHNOLOGY. and a citizen of Korean
3. OGUMA, Naomi residing at c/o DAINICHISEIKA COLOR & CHEMICALS MFG. CO., LTD. and a citizen of Japan
4. HIRATA, Naoki residing at c/o DAINICHISEIKA COLOR & CHEMICALS MFG. CO., LTD. and a citizen of Japan
5. KONO, Hisao residing at c/o DAINICHISEIKA COLOR & CHEMICALS MFG. CO., LTD. and a citizen of Japan

(hereinafter called "THE UNDERSIGNED") have made an invention and have executed an application for Letters Patent of the United States for this invention which was filed on _____, entitled ORGANIC SEMICONDUCTOR PARTICULATE MATERIAL, ORGANIC SEMICONDUCTOR THIN-FILM, DISPERSION LIQUID FOR FORMING ORGANIC SEMICONDUCTOR FILM, METHOD FOR PRODUCING ORGANIC SEMICONDUCTOR THIN-FILM, AND ORGANIC THIN-FILM TRANSISTOR, and which has been given application serial number _____;

and

WHEREAS SHINSHU UNIVERSITY (hereinafter "ASSIGNEE") a corporation organized under the laws of Japan and having an office and place of business at 1-1, Asahi 3-chome, Matsumoto-shi, Nagano 390-8621, Japan and DAINICHISEIKA COLOR & CHEMICALS MFG. CO., LTD. (hereinafter "ASSIGNEE") a corporation organized under the laws of Japan and having an office and place of business at 7-6, Nihonbashi Bakuro-cho 1-chome, Chuo-ku, Tokyo 103-8383, Japan wish(es) to acquire the entire right, title and interest in and to said invention and patent application and any Letters Patent to be obtained therefor;

NOW, THEREFORE, for and in consideration of the sum of One Dollar (\$1.00) and other good and valuable consideration, the receipt and sufficiency of which is hereby acknowledged, THE UNDERSIGNED hereby sell, assign, and transfer to the ASSIGNEES, its successors, legal representative and assigns, the entire right, title and interest for the United States in and to the invention disclosed in said application, and in and to said application, as well as to all divisions, continuations, or renewals thereof, all Letters Patent which may be granted therefrom, and all reissues or extensions of such patents, and THE UNDERSIGNED hereby authorize and request the Commissioner of Patents of the United States to issue all Letters Patent for said invention to the

ASSIGNEES of the entire right, title and interest in and to the same, in accordance with the terms of this instrument.

THE UNDERSIGNED hereby agree that THE UNDERSIGNED, their executors and legal representatives will make, execute and deliver (without charge but at the expense of the ASSIGNEES) any and all other instruments in writing including any and all further application papers, affidavits, assignments and other documents, and will communicate to said ASSIGNEES, its successors and representatives all facts known to the UNDERSIGNED relating to said invention and the history thereof and will testify in all legal proceedings and generally do all things which may be necessary or desirable to vest the ASSIGNEES, its successors or assigns, the entire right, title and interest in and to the said invention, patent applications, Letters Patent, rights, titles, benefits, privileges, and advantages hereby sold, assigned and conveyed, or intended so to be.

THE UNDERSIGNED represent and agree with said ASSIGNEES, its successors and assigns, that no assignment, grant, mortgage, license or other agreement affecting the rights and property herein conveyed has been or will be made to others by the UNDERSIGNED, and that full right to convey the same as herein expressed is possessed by the UNDERSIGNED.

IN TESTIMONY WHEREOF, THE UNDERSIGNED have hereunto set their hand on the dates indicated below.


1. Signature ICHIKAWA, Musubu

23 January 2013
Date


2. Signature JEON, Hyeon-Gu

23 January 2013
Date

3. Signature OGUMA, Naomi

23 January 2013
Date

4. Signature HIRATA, Naoki

23 January 2013
Date

5. Signature KONO, Hisao

23 January 2013
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(hereinafter called "THE UNDERSIGNED") have made an invention and have executed an application for Letters Patent of the United States for this invention which was filed on _____, entitled ORGANIC SEMICONDUCTOR PARTICULATE MATERIAL, ORGANIC SEMICONDUCTOR THIN-FILM, DISPERSION LIQUID FOR FORMING ORGANIC SEMICONDUCTOR FILM, METHOD FOR PRODUCING ORGANIC SEMICONDUCTOR THIN-FILM, AND ORGANIC THIN-FILM TRANSISTOR, and which has been given application serial number _____;

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NOW, THEREFORE, for and in consideration of the sum of One Dollar (\$1.00) and other good and valuable consideration, the receipt and sufficiency of which is hereby acknowledged, THE UNDERSIGNED hereby sell, assign, and transfer to the ASSIGNEES, its successors, legal representative and assigns, the entire right, title and interest for the United States in and to the invention disclosed in said application, and in and to said application, as well as to all divisions, continuations, or renewals thereof, all Letters Patent which may be granted therefrom, and all reissues or extensions of such patents, and THE UNDERSIGNED hereby authorize and request the Commissioner of Patents of the United States to issue all Letters Patent for said invention to the

ASSIGNEES of the entire right, title and interest in and to the same, in accordance with the terms of this instrument.

THE UNDERSIGNED hereby agree that THE UNDERSIGNED, their executors and legal representatives will make, execute and deliver (without charge but at the expense of the ASSIGNEES) any and all other instruments in writing including any and all further application papers, affidavits, assignments and other documents, and will communicate to said ASSIGNEES, its successors and representatives all facts known to the UNDERSIGNED relating to said invention and the history thereof and will testify in all legal proceedings and generally do all things which may be necessary or desirable to vest the ASSIGNEES, its successors or assigns, the entire right, title and interest in and to the said invention, patent applications, Letters Patent, rights, titles, benefits, privileges, and advantages hereby sold, assigned and conveyed, or intended so to be.

THE UNDERSIGNED represent and agree with said ASSIGNEES, its successors and assigns, that no assignment, grant, mortgage, license or other agreement affecting the rights and property herein conveyed has been or will be made to others by the UNDERSIGNED, and that full right to convey the same as herein expressed is possessed by the UNDERSIGNED.

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1. Signature ICHIKAWA, Musubu 23 January 2013
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2. Signature JEON, Hyeon-Gu 23 January 2013
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小 熊 尚 実
3. Signature OGUMA, Naomi 23 January 2013
Date

平 田 直 毅
4. Signature HIRATA, Naoki 23 January 2013
Date

河 野 封 夫
5. Signature KONO, Hisao 23 January 2013
Date